



# 3D Packaging and Integration Global Technical Committee

## Japan TC Chapter

### Meeting Summary and Minutes

Japan Standards Fall Meeting 2023

September 5, 2023, 13:30-15:30[JST]

OVTCCM

#### TC Chapter Announcements

*Next TC Chapter Meeting*

Friday, January 26 , 2024 15:00-17:00

OVTCCM

#### Table 1 Meeting Attendees

*Italics indicate virtual participants*

**Co-Chairs:** Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI), Haruo Shimamoto (AIST)

**SEMI Staff:** Mami Nakajo

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
<i>AIST</i>	<i>Shimamoto</i>	<i>Haruo</i>	Nagase	Takahashi	Atsushi
<i>AiT</i>	<i>Kato</i>	<i>Kazunori</i>	Shin-Etsu Polymer Co., Ltd.	Odashima	Satoshi
<i>iNEMI</i>	<i>Tsuruya</i>	<i>Masahiro</i>	<i>Self</i>	<i>Takahashi</i>	<i>Mark</i>
<i>KOKUSAI ELECTRIC CORPORATION</i>	<i>Matsuda</i>	<i>Mitsuhiro</i>	SEMI Japan	Kanno	Hirofumi
SEMI Japan	Akiko	Yoshida	SEMI Japan	Osawa	Naoko

#### Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

#### Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

#### Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
7019	Reapproval of SEMI G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)	<b>Passed as balloted</b>
7020	Reapproval of SEMI G94-0113 (Reapproved 1118) Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer	<b>Passed as balloted</b>

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.



#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 5 Ratification Ballot Results**

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&amp;R Action</i>	<i>A&amp;R Forms</i>
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

**Table 6 Activities Approved by the GCS between meetings of the TC Chapter**

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

**Table 7 Authorized Activities**

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

**Table 8 Authorized Ballots**

<i>#</i>	<i>When</i>	<i>TF</i>	<i>Details</i>
None			

**Table 9 SNARF(s) Granted a One-Year Extension**

<i>#</i>	<i>TF</i>	<i>Title</i>	<i>Expiration Date</i>
None			

**Table 10 SNARF(s) Abolished**

<i>#</i>	<i>TF</i>	<i>Title</i>
None		

**Table 11 Standard(s) to receive Inactive Status**

<i>Standard Designation</i>	<i>Title</i>
None	

**Table 12 New Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
None		

**Table 13 Previous Meeting Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20230621-01	SEMI Staff	To submit the ballot review sheets to the A&R

## 1 Welcome, Reminders, and Introductions

Kato Kazunori (AiT) called the meeting to order at 1330. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

**Attachment:** 1.2\_Required Element Nov 2022\_E+J (new template),

## 2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

**Motion:** Haruo Shimamoto ( AIST-National Institute of Advanced Industrial and Technology)

**By / 2<sup>nd</sup>:** Mitsuhiro Matsuda (KOKUSAI ELECTRIC CORPORATION)

**Discussion:** None

**Vote:** 5 in favor and 0 opposed. Motion passed.

**Attachment:** 2\_20230621\_3DPI-Japan\_MeetingMinutes\_approved

## 3 Liaison Reports

### 3.1 3D Packaging & Integration North America TC Chapter

Mami Nakajo (SEMI Japan) reported for the 3D Packaging & Integration North America TC Chapter activity status based on the report as attached.:

**Attachment:** 3.1\_NA 3DP&I Liaison Report July2023 v1,

### 3.2 3D Packaging & Integration Taiwan TC Chapter

Mami Nakajo (SEMI Japan) reported for the 3D Packaging & Integration Taiwan TC Chapter activity status based on the report as attached.:

**Attachment:** 3.2\_3D P&I TW Liaison Report\_20220902\_v1,

## 4 SEMI Staff Report

Mami Nakajo (SEMI) explained the SEMI Staff Report based on the report as attached.:

**Attachment:** 4. Staff Report July 2023 v3 (1),

## 5 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

### 5.1 Cycle 5-2023 submitted by the Japan TC Chapter

5.1.1 Document #7019 - Reapproval of SEMI G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)



The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

**Attachment:** 5.1.1\_7019\_Ballot Report Template\_final

5.1.2 Document # 7020 - Reapproval of SEMI G94-0113 (Reapproved 1118) Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer

The ballot passed TC Chapter review as balloted. See attachment for ballot adjudication.

**Attachment:** 5.1.2\_7020\_Ballot Report Template\_Final

**Action Item 20230905-01:** (SEMI Staff) To submit the ballot review sheets to the A&R

## 6 Subcommittee and Task Force Reports

### 6.1 GCS Report

- None

### 6.2 3D Packaging & Integration 5 Year Review Task Force >

Masahiro Tsuruya (iNEMI) reported the 3D Packaging & Integration 5 Year Review Task Force status as attached.

**Attachment:** 6.2\_TF Report - 5yrs Review TF v2023\_9,

### 6.3 3DS IC Bonded Layer Inspection Metrology Task Force

Haruo Shimamoto (AIST) reported for the 3DS IC Bonded Layer Inspection Metrology Task Force. The TF is currently working on the issues regarding Alignment mark.

**Attachment:** 6.3\_230905 ActivitiesReport\_3DSIC-InspectionTF\_Presentation,

### 6.4 Panel Level Packaging (PLP) Glass Carrier Task Force

Mark Takahashi (SELF) reported there is no update.

### 6.5 Steering Working Group

Haruo Shimamoto (AIST) and Masahiro Tsuruya (iNEMI) reported the 3D Packaging & Integration 5 Year Review Task Force status as attached.

**Attachment:** 6.5\_TF Report - Steering WG v2023\_9draft,

Hirofumi Kanno (SEMI Japan) reported on the attached document regarding the Workshop organized by Steering Working Group to be held at SEMICON Japan.

Japan 3DP&I Committee confirmed the Workshop to be held during SEMICON Japan.

Workshop program is under discussion at the prep team, and Haruo Shimamoto (AIST) will present the advanced packaging technologies overview first, then 3 panelist will share the critical packaging challenges from the material, equipment and processes. Panel discussion is planned after the presentation

**Attachment:** 2023\_Steering WG Workshop\_R5,

## 7 Old Business

### 7.1 Project Period Review-

None

### 7.2 5 Year Review Check

None

## 8 New Business

### 8.1 Proposal of New Activity

None

## 9 Action Item Review

### 9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20230621-01	SEMI Staff	To submit the ballot review sheets to the A&R>Done

### 9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20230905-01	SEMI Staff	To submit the ballot review sheets to the A&R

## 10 Next Meeting and Adjournment

The next meeting is scheduled for Friday, January 26,2024,15:00-17:00 [JST] @ OVTCCM

See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: [15:30]>.

Respectfully submitted by:

Mami Nakajo

Coordinator

SEMI Japan

Phone: +81.3.3222.5949

Email: [mnakajo@semi.org](mailto:mnakajo@semi.org)

Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	October 11,2023
Masahiro Tsuruya (iNEMI), Co-chair	October 12, 2023
Haruo Shimamoto(AIST), Co-chair	October 12, 2023



**Table 14 Index of Available Attachments#1**

<i>Title</i>	<i>Title</i>
1.2_Required Element Nov 2022_E+J (new template)	5.1.2_7020_Ballot Report Template_Final
2_20230621_3DPI-Japan_MeetingMinutes_approved	6.2_TF Report - 5yrs Review TF v2023_9
3.1_NA 3DP&I Liaison Report July2023 v1	6.3_230905 ActivitiesReport_3DSIC- InspectionTF_Presentation
3.2_3D P&I TW Liaison Report_20220902_v1	6.5_TF Report - Steering WG v2023_9draft
4. Staff Report July 2023 v3 (1)	2023_Steering WG Workshop_R5
5.1.1_7019_Ballot Report Template_final	

Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.